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(54) **CIRCUIT BOARD ASSEMBLY, MANUFACTURING METHOD, AND ELECTRONIC DEVICE**

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(57) **ABSTRACT**

A circuit board assembly, a manufacturing method are provided. The circuit board assembly includes a flexible printed circuit board and a printed circuit board, a pad for disposing a welding piece is provided on the printed circuit board, the flexible printed circuit board includes a main body and a welding part disposed on an inner wall of a through hole of the main body, the through hole includes a recessing part and a connection segment connected to a bottom wall of the recessing part, the recessing part is disposed on a side that is of the connection segment and that is away from the pad, and an end that is of the connection segment and that is away from the recessing part faces the pad, so that the welding piece overflows into the recessing part through the connection segment, and welds the welding part to the pad.